

产品规格承认书

SPECIFICATIONS

客户:

CUSTOMER: _____

产品名称:

DESCRIPTION: _____ 双极天线

客户型号:

CUSTOMER PART NO: _____

产品型号:

OUR MODEL NO: _____ **PBX1608MC01**

日期:

DATE: _____

确认签字, 盖章后请返回承认书一份

PLEASE RETURN TO US ONE COPY OF “SPECIFICATION FOR APPROVAL”
WITH YOUR APPROVED SIGNATURES

核准		审核	刘飞	制作	刘小美
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客户承认签印	
日期	

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DESIGNED BY: Sera	APPROVED BY: XD		
TITLE: CHIP2450-1608 Specification		DOCUMENT NO.	SPEC REV.
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PBX1608MC01 Specification

1. Features:

- Stable and reliable in performances
- Low profile, compact size
- RoHS compliance
- SMT processes compatible

2. APPLICATIONS:

- ISM 2.4 GHz applications
- ZigBee/BLE applications
- Bluetooth earphone systems
- Hand-held devices when WiFi/Bluetooth functions are needed, e.g., Smart phones
- IEEE802.11 b/g/n
- Wireless PCMCIA cards or USB dongles

3. Part Number Information

AN 1608 S 24 LS
 A B C D E

A	贴片陶瓷天线	Antenna
B	尺寸	1.5X0.8mm
C	天线类型	S: 双极 D: 单极
D	频率	2.4 ~ 2.5GHz
E	产品类型	LS

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4. Product dimensions:

1608 双极天线

Figure	Symbol	Dimension (mm)
	L (长)	1.5 ± 0.10
	W (宽)	0.8 ± 0.10
	T (厚度)	0.50 ± 0.10
	A (电极宽度)	0.2 ± 0.10

5. Electrical Specification:

Specification		
Part Number	AN1608S24LS	
Central Frequency	2450	MHz
Bandwidth	120 (Min.)	MHz
Return Loss	-6.5 (Max)	dB
Peak Gain	1.66	dBi
Impedance	50	Ohm
Operating Temperature	$-40^{\circ}\text{C} \sim +85^{\circ}\text{C}$	C
Maximum Power	4	W
Resistance to Soldering Heats	10 (@ 260C)	sec.
Polarization	Linear	
Azimuth Beamwidth	Omni-directional	
Termination	Ni / Sn (Leadless)	

Remark : Bandwidth & Peak Gain was measured under evaluation board of next page

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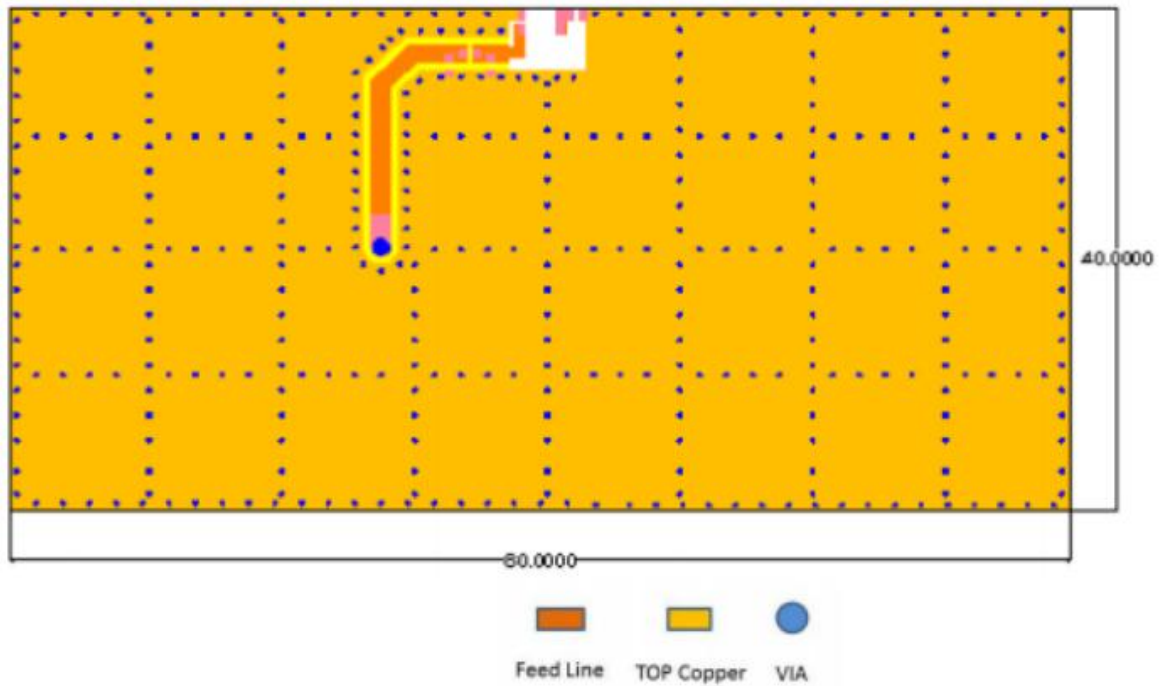
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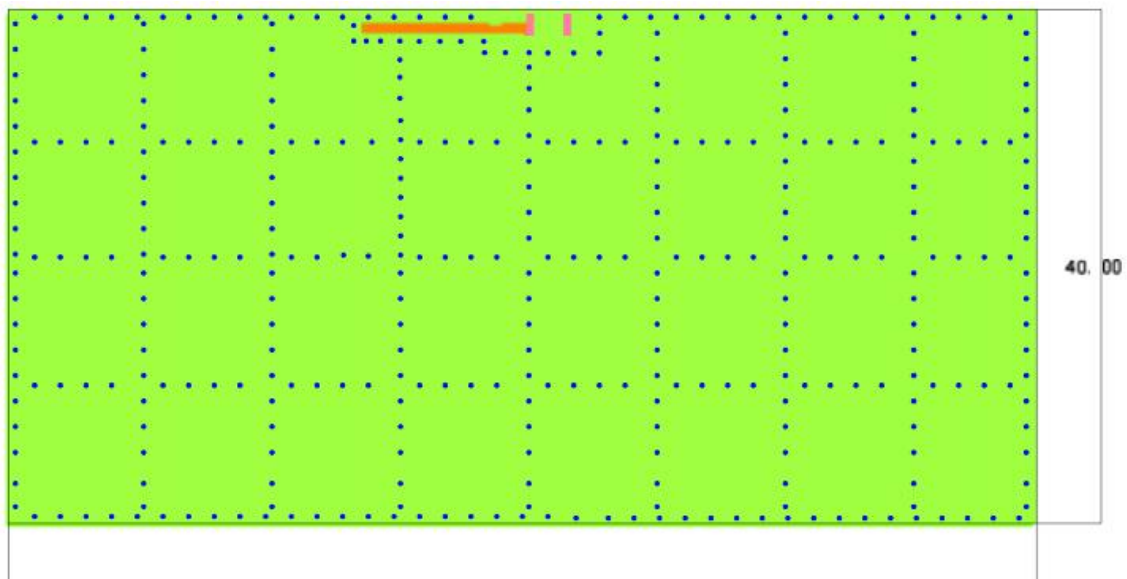
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6. 1608 双极天线推荐 PCB



2nd Evaluation Board Dimension



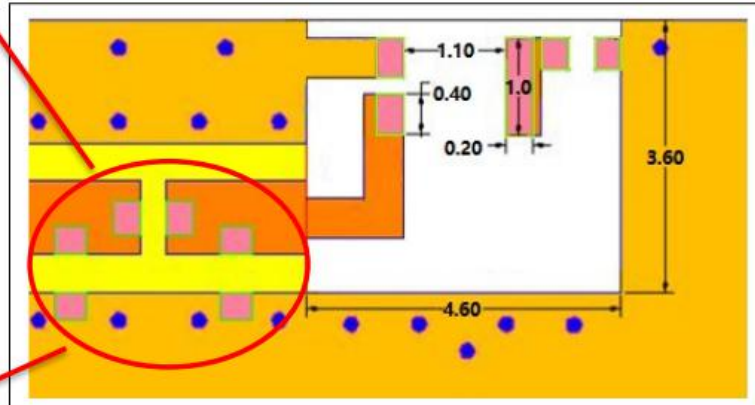
匹配元件建议使用村田 $\pm 1\%$ 以下的电感、电容

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净空区域 (Size=4.6*3.6mm)

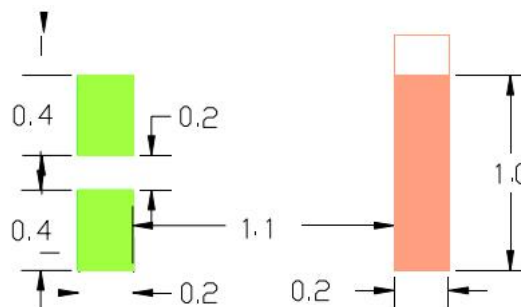


50 ohm transmission Line

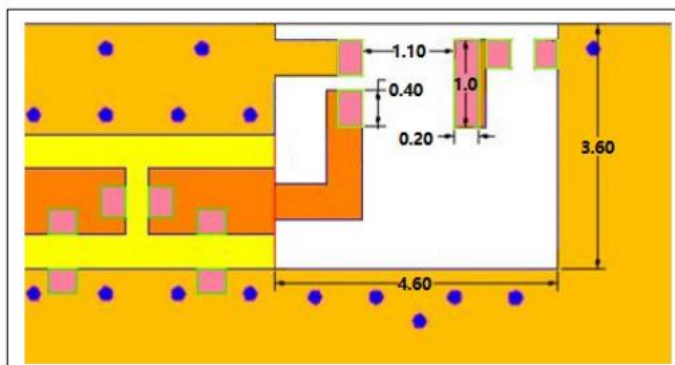


Matching Circuit

FootPrint (Unit : mm)



2 Layout Dimensions in Clearance area (Size=8.0*3.0mm)



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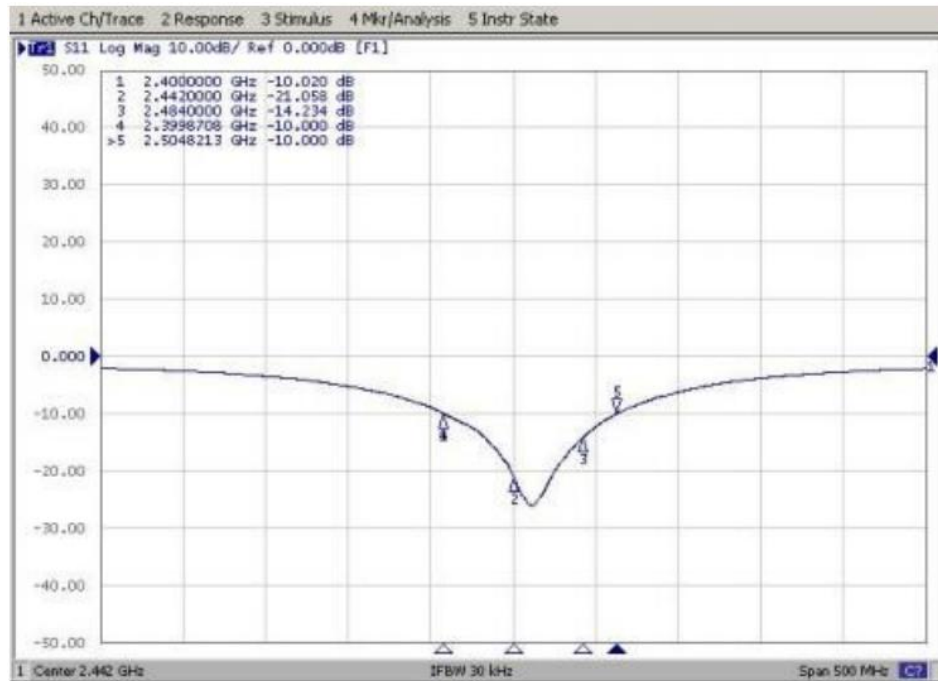
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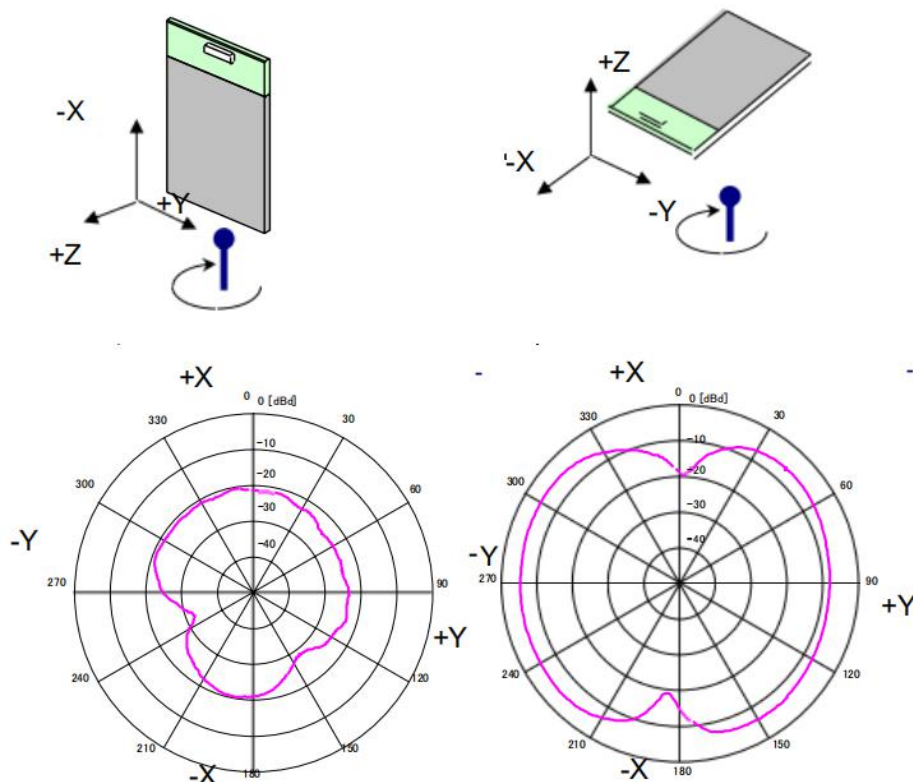
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7. Measurement Results

Return Loss



7.2 Radiation Pattern



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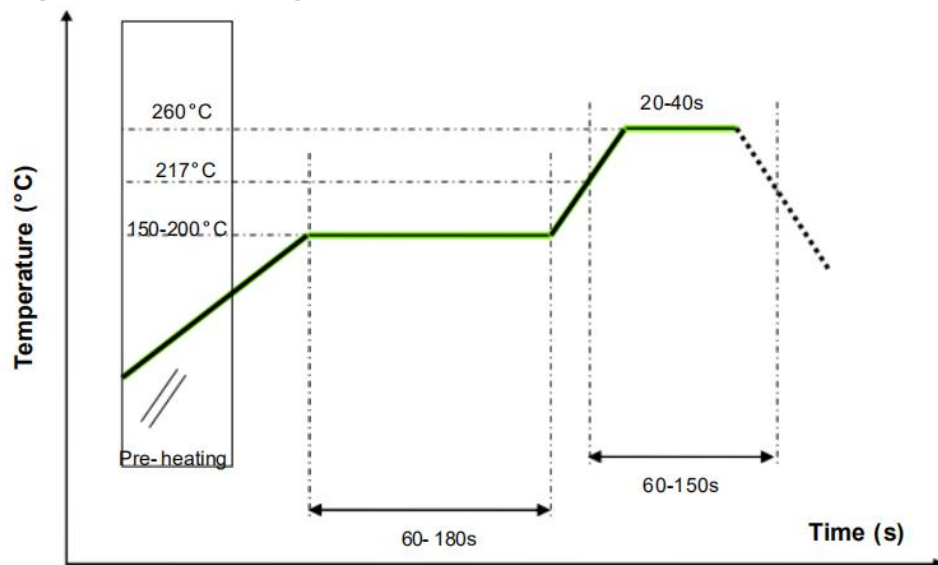
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8. Reliability and Test Conditions

Test item	Test condition / Test method	Specification
Solderability JIS C 0050-4.6 JESD22-B102D	*Solder bath temperature : $235 \pm 5^{\circ}\text{C}$ *Immersion time : 2 ± 0.5 sec Solder : Sn3Ag0.5Cu for lead-free	At least 95% of a surface of each terminal electrode must be covered by fresh solder.
Leaching (Resistance to dissolution of metallization) IEC 60068-2-58	*Solder bath temperature : $260 \pm 5^{\circ}\text{C}$ *Leaching immersion time : 30 ± 0.5 sec Solder : SN63A	Loss of metallization on the edges of each electrode shall not exceed 25%.
Bending test JIS C 0051- 7.4.1	The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 1 mm/s per second until the deflection becomes 1mm/s and then pressure shall be maintained for 5 ± 1 sec. Measurement to be made after keeping at room temperature for 24 ± 2 hours	No mechanical damage. Electrical specification shall satisfy the descriptions in electrical characteristics under the operational temperature range within $-40 \sim 85^{\circ}\text{C}$.
Resistance to soldering heat JIS C 0050-5.4	*Preheating temperature : $120 \sim 150^{\circ}\text{C}$, 1 minute. *Solder temperature : $270 \pm 5^{\circ}\text{C}$ *Immersion time : 10 ± 1 sec Solder : Sn3Ag0.5Cu for lead-free Measurement to be made after keeping at room temperature for 24 ± 2 hrs	No mechanical damage. Electrical specification shall satisfy the descriptions in electrical characteristics under the operational temperature range within $-40 \sim 85^{\circ}\text{C}$. Loss of metallization on the edges of each electrode shall not exceed 25%.

9. Soldering and Mounting



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10. 天线应用注意事项

- ☐ 如果空间允许, 最好不要选择太小尺寸的天线。
- ☐ 最好天线与附近物体之间有一定的净空区; 否则匹配调节将会变得困难, 辐射模式会受到严重扭曲。
- ☐ 天线的下方不应出现线路布局、接地层。
- ☐ 天线不应和金属物体放置太近, 比如电池、芯片等, 不应与电池等金属物有重叠。
- ☐ 注意内部缆线(如电池电源线)最好不要太靠近天线。
- ☐ 双极天线需要有合理的接地面才能发挥最好效果。
- ☐ 在最终产品方案上进行天线匹配, 可以减小调节周期; 而在光板上往往需要反复调节。
- ☐ 如果没有经过匹配, 相同的天线放置完全不一样的布局板上可能无法正常工作。
- ☐ 不要使用金属外壳或带金属的塑料外壳盖在天线周围。
- ☐ 不要使用很细的天线馈电线, 馈线应有一定的宽度, 不应小于 0.1mm。
- ☐ 根据 PCB 的厚度和介电常数计算馈线阻抗, 50 欧姆会使天线调节较为容易
- ☐ 片式天线装配应尽可能远离电池、EMI 防护材料、折叠扬声器、金属铆钉、LCD 显示屏等。

11. Storage and Transportation Information

Storage Conditions

To maintain the solderability of terminal electrodes:

1. Temperature and humidity conditions: - 10~ 40C and 30~70% RH.
2. Recommended products should be used within 6 months from the time of delivery.
3. The packaging material should be kept where no chlorine or sulfur exists in the air.

Transportation Conditions

1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
3. Bulk handling should ensure that abrasion and mechanical shock are minimized.

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